

Enhancing Solar Cell Metallization through Laser-Optimized Screen-Printing Technology

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A potential strategy to further enhance the screen-printing process is by reducing the width of printed electrical contacts and minimizing silver consumption by using an ultraviolet (UV) picosecond laser to structure the screen openings. In this work, we successfully lasered a busbarless grid layout with 120 finger openings onto a knotless (0°) screen with a mesh count of 520 wires/inch and wire diameter of 11 μm in just ten minutes and sixteen seconds, significantly decreasing the time required to structure a screen. The average width of the printed contact from the lasered screen on a silicon heterojunction (SHJ) wafer was $w_f = 23 \mu\text{m}$, comparable to 21 μm from a reference screen.

Introduction and Motivation

Screen-printing goals:

- Reducing silver consumption [1] and width of electrical contact [2]
- Improve screen fabrication process: increase screen lifetime and reduce cost

Approach:

- Structuring of grid layout on a dual barrier layer composed of polyimide (PI) and liquid photopolymer by means of laser ablation

Advantages:

- PI: increase screen lifetime
- Liquid photopolymer: flexible layer to ensure a thorough channel edge sealing

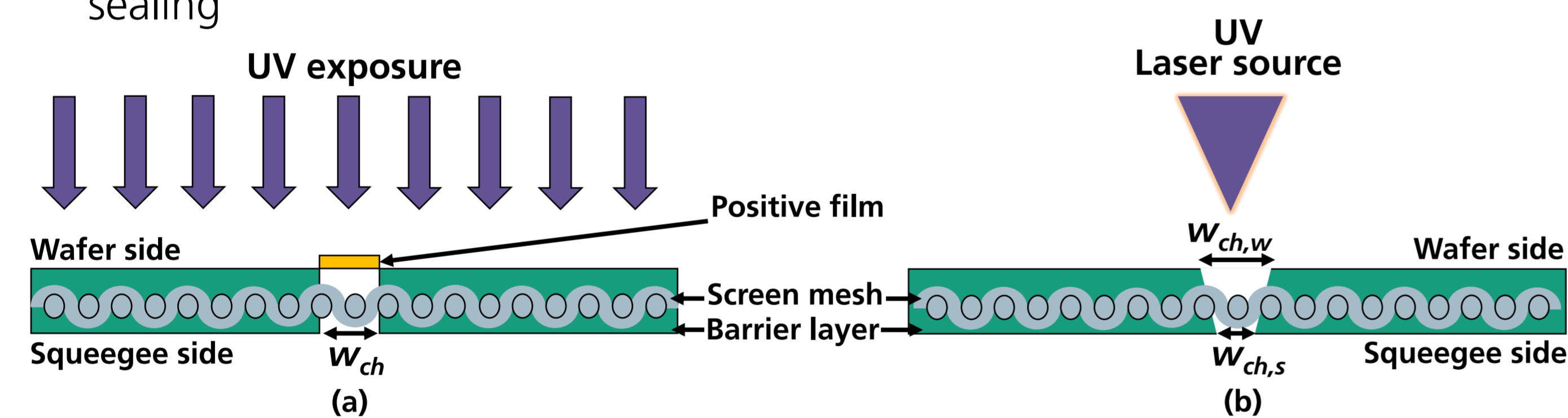


Fig. 1: Schematic representation of screen openings created by (a) traditional process (b) laser process – on the wafer side of the screen [3]

Experimental Approach

Part A: Screen structuring via laser processing

- Laser parameter variation test conducted by varying the pulse energy (E_p), pulse pitch (p_p), line to line pitch (l/l), number of passes (r) and repetition rate
- Laser structuring full grid layout on Screen A with optimal laser parameters

Part B: Screen-printing of laser structured screens

- Screen-printing M2 SHJ precursors with Screen A and Screen B (reference) using a low temperature (LT) paste and at varied printing speeds ($v_{printing}$)
- Finger width (w_f) and height (h_f) measured: 45 points per group

| UV-Vis Spectroscopy | | | | M2 HJT precursors | | | | |
|---|---------------------------|-------|-------|---|----------------------|--|--|----------------------------------|
| Choosing an optimal laser source | | | | Rear side metallization – LT Ag paste | | | | |
| Test screen: 360/16/0° | | | | Drying at $T_{drying} = 200^\circ\text{C}$ for 2 min | | | | |
| Laser parameter variation | | | | Samples weighed | | | | |
| Repetition rate | r | p_p | l/l | E_p | Screen A (520/11/0°) | | | Screen B (reference) (520/11/0°) |
| 2D optical microscopy | | | | Front side metallization – LT Ag paste | | | | |
| Mesh damage assessment | Opening width measurement | | | Optimal laser parameter chosen | | | | |
| Screen A: 520/11/0° | | | | Screen B: 520/11/0° | | | | |
| Lasing of full grid layout with optimal laser parameters (120 finger openings, 0BB) | | | | Printing speeds: 150 mm/s, 300 mm/s, 150 mm/s, 300 mm/s | | | | |
| 2D optical microscopy | | | | Samples weighed | | | | |
| Mesh damage assessment | Opening width measurement | | | Curing at $T_{curing} = 200^\circ\text{C}$ for 2 min | | | | |
| | | | | 3D Confocal microscopy of printed electrical contacts (fingers) | | | | |

Fig. 2: Summary of the experimental plan for (a) Part A and (b) Part B

[1] S. Tepner, A. Lorenz, 'Printing technologies for silicon solar cell metallization: A comprehensive review', Progress in Photovoltaics, Vol. 31, Issue 6, 2023
 [2] Wenzel et al., Progress with screen printed metallization of silicon solar cells - Towards 20 μm line width and 20 mg silver laydown for PERC front side contacts, Solar Energy Materials and Solar Cells, Volume 244, 2022
 [3] Adapted from A. Nair, et al., 'Progress on screen-printed metallization by improving the screen manufacturing process with laser technology', EUPVSEC Lisbon, Poster, 2023

Results

Part A : Screen structuring via laser processing

- Successful laser structuring of full cell layout in 10 minutes 16 seconds
- Average taper ratio (TR) of lased channels: $TR = w_{ch,w} / w_{ch,s} = 1.8$

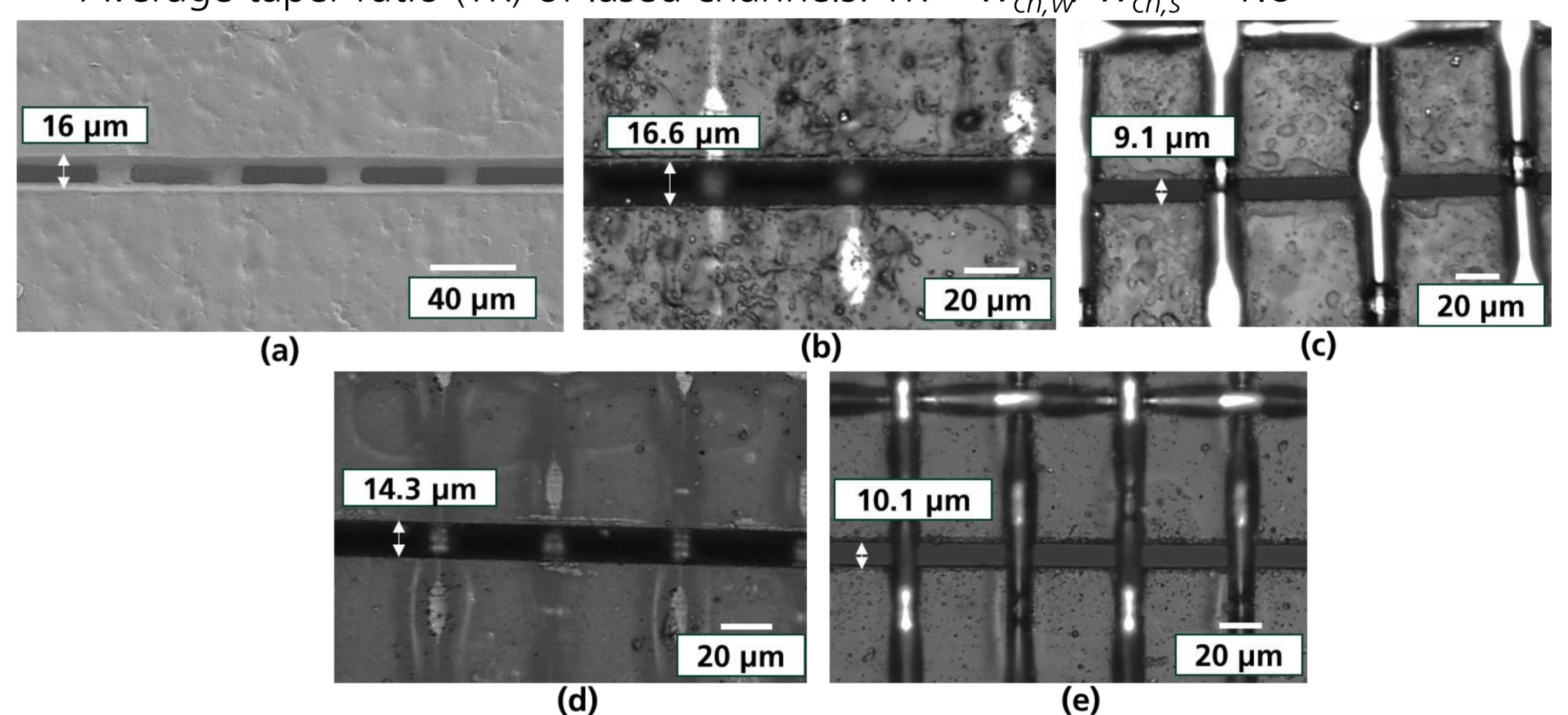


Fig. 3: Screen A: (a) SEM image of laser structured opening, image from (b) wafer side (c) squeegee side. Screen B: Opening from (d) wafer side (e) squeegee side

| Screen | Mesh | Layout | Avg $w_{ch,w}$ (μm) | Avg $w_{ch,s}$ (μm) | TR |
|--------|-----------|------------|---------------------|---------------------|-----|
| A | 520/11/0° | 120 F, 0BB | 16.6 | 9.2 | 1.8 |
| B | 520/11/0° | 120 F, 0BB | 15.4 | 10.4 | 1.5 |

Table 1: Summary of average opening channel widths and TR for Screen A and Screen B

Part B: Screen-printing of laser structured screens

- Avg $w_f = 23 \pm 2 \mu\text{m}$ from Screen A, comparable to Screen B $w_f = 21 \pm 4 \mu\text{m}$

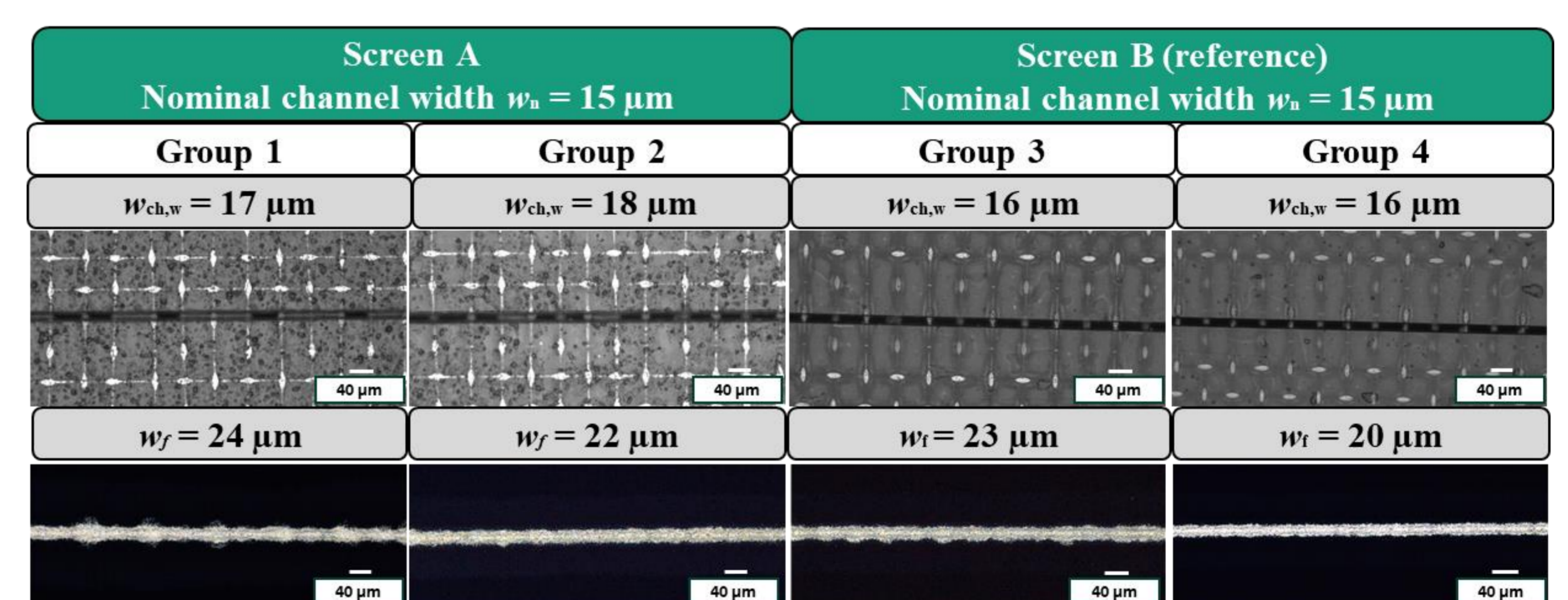


Fig. 4: Microscopic images of Screen A and Screen B and the fingers printed from respective opening

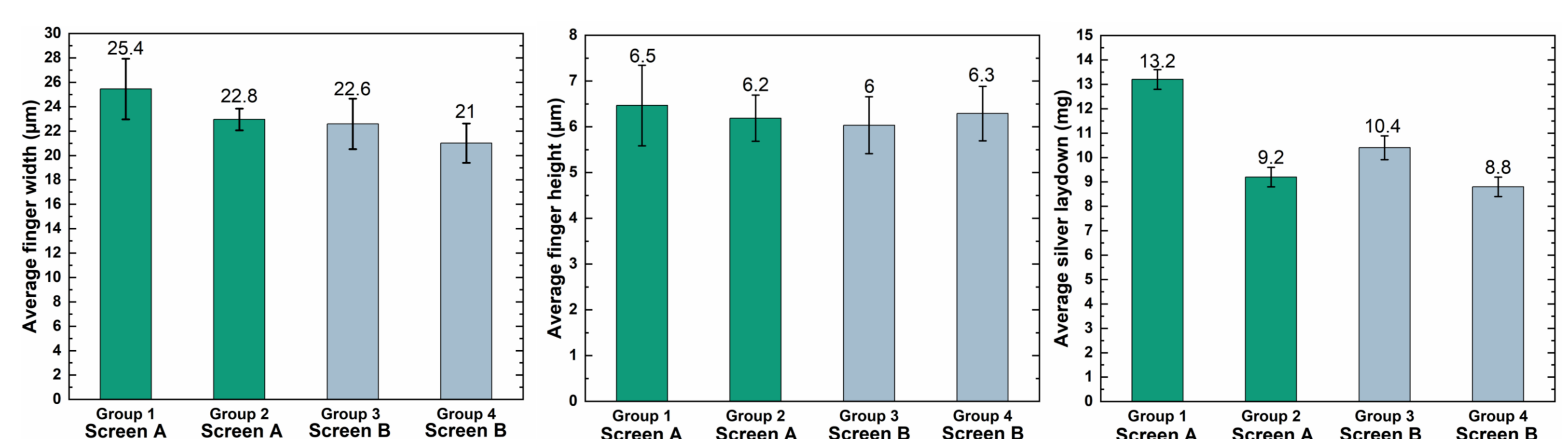


Fig. 5: Average finger width, height and silver laydown of wafers printed from Screen A and Screen B

Summary and Conclusion

- Full cell grid layout successfully laser structured on a 520/11/0° screen with optimal laser parameters in **10 minutes**.
- Fine line front side metallization of SHJ solar cells with $w_f = 23 \pm 2 \mu\text{m}$ screen-printed from laser structured screen.

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